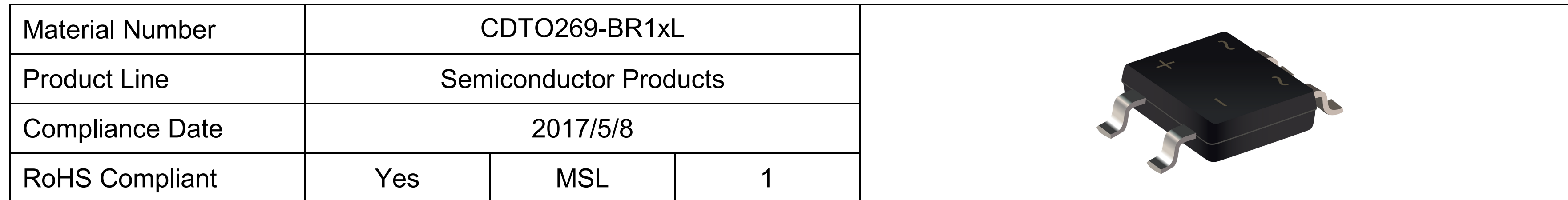
MATERIAL DECLARATION SHEET



Material Number	CDTO269-BR1xL		
Product Line	Semiconductor Products		
Compliance Date	2017/5/8		
RoHS Compliant	Yes	MSL	1

No.	Construction Element(subpart)	Homogeneous Material	Material weight [mg]	Homogeneous Material	CASRN	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
				Substances	if applicable			
1	Chip (die)	Other inorganic materials	0.003	Nickel	7440-02-0	**1.000000%**	0.003000%	0.300000%
			0.0345	Gold	7440-57-5	**11.500000%**	0.034500%	
			0.075	Polydimethylsiloxane rubber	63394-02-5	**25.000000%**	0.075000%	
			0.1875	Silicon	7440-21-3	**62.500000%**	0.187500%	
2	Die attach	Lead and Lead alloys	0.03175	Silver	7440-22-4	**2.500000%**	0.031750%	1.270000%
			0.0635	Tin	7440-31-5	**5.000000%**	0.063500%	
			1.17475	Lead(2)	7439-92-1	**92.500000%**	1.174750%	
3	Encapsulation	EP (Epoxy resin)	0.12378	Carbon black	1333-86-4	**0.300000%**	0.123780%	41.260000%
			11.67658	Epoxy resin 89	26335-32-0	**28.300000%**	11.676580%	
			29.45964	Quartz sand	60676-86-0	**71.400000%**	29.459640%	
4	Lead finish	Tin plating	0.0069	Copper	7440-50-8	**0.500000%**	0.006900%	1.380000%
			0.0414	Silver	7440-22-4	**3.000000%**	0.041400%	
			1.3317	Tin	7440-31-5	**96.500000%**	1.331700%	
5	Lead frame	Copper	55.79	Copper	7440-50-8	**100.000000%**	55.790000%	55.790000%
		Total weight	100					

This Document was updated on: 2017/5/8

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Important remarks:

1. It is the responsibility of the user to verify they are accessing the latest version.
2. Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

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